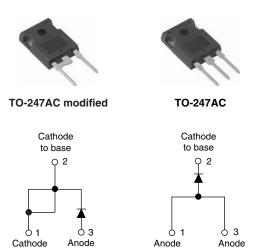


Vishay Semiconductors

Ultrafast Soft Recovery Diode, 60 A FRED Pt®



www.vishay.com

PRODUCT SUMMARY						
Package	TO-247AC,					
. donago	TO-247AC modified (2 pins)					
I _{F(AV)}	60 A					
V_{R}	600 V					
V _F at I _F	1.68 V					
t _{rr} typ.	See Recovery table					
T _J max.	175 °C					
Diode variation	Single die					

VS-60APU06HN3

VS-60EPU06HN3

FEATURES

- · Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- AEC-Q101 qualified, meets JESD 201 class 1A whisker test
- Material categorization:
 For definitions of compliance please see www.vishav.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

DESCRIPTION/APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Cathode to anode voltage	V _R		600	V			
Continuous forward current	I _{F(AV)}	T _C = 116 °C	60				
Single pulse forward current	I _{FSM}	T _C = 25 °C	600	Α			
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	120				
Operating junction and storage temperatures	T _J , T _{Stg}		- 55 to 175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-		
		I _F = 60 A	-	1.35	1.68	V	
Forward voltage	V_{F}	I _F = 60 A, T _J = 125 °C	-	1.20	1.42		
		I _F = 60 A, T _J = 175 °C	-	1.11	1.30		
Deviana leeka aa ay maant		$V_R = V_R$ rated	-	-	50		
Reverse leakage current	I _R	T _J = 150 °C, V _R = V _R rated	-	-	500	μΑ	
Junction capacitance	C _T	V _R = 600 V	-	39	-	pF	



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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 A, dI_F/dt = 20$	00 A/μs, V _R = 30 V	-	34	45		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	81	-	ns	
		T _J = 125 °C		ı	164	-		
Peak recovery current	1	T _J = 25 °C	I _F = 60 A dI _F /dt = 200 A/μs	ı	7.4	-	Α	
reak recovery current	I _{RRM}	T _J = 125 °C	$V_{\rm R} = 200 \text{ V}$	-	17.0	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C	N - 200 V	-	300	-	nC	
		T _J = 125 °C		-	1394	-		

THERMAL - MECHAN	THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Thermal resistance, junction to case	R _{thJC}		-	-	0.63	K/W		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.2	-	N/VV		
Weight			-	5.5	-	g		
Weight			-	0.2	-	OZ.		
Mounting torque			1.2 (10)	-	2.4 (20)	N ⋅ m (lbf ⋅ in)		
Marking device		Case style TO-247AC modified	47AC modified 60EPU06H					
ivial killig device		Case style TO-247AC		60AF	U06H			

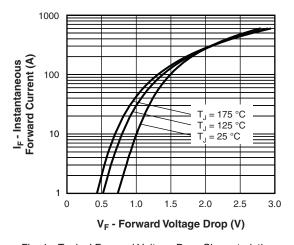


Fig. 1 - Typical Forward Voltage Drop Characteristics

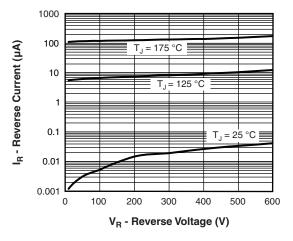


Fig. 2 - Typical Values of Reverse Current vs.
Reverse Voltage

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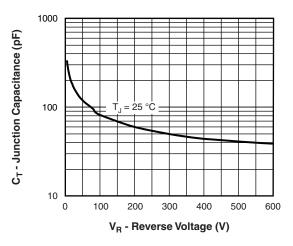


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

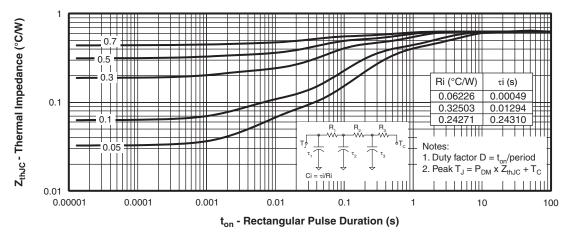


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

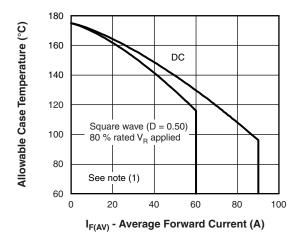


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

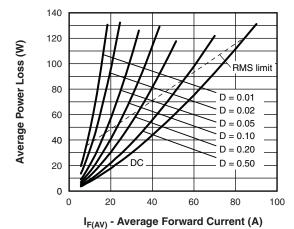


Fig. 6 - Forward Power Loss Characteristics

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VS-60EPU06HN3, VS-60APU06HN3

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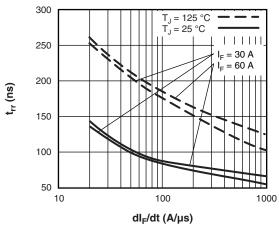


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

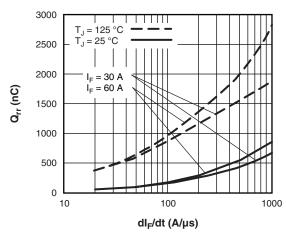


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{th,JC}; Pd = Forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = Inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

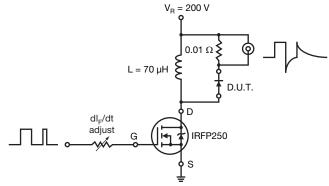
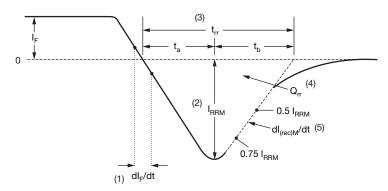


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{rr}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \boldsymbol{Q}_{rr} area under curve defined by \boldsymbol{t}_{rr} and \boldsymbol{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dl_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

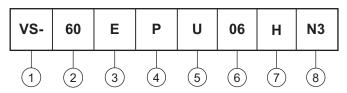
Fig. 10 - Reverse Recovery Waveform and Definitions



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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (60 = 60 A)

Circuit configuration:

• E = Single diode

• A = Single diode, 3 pins

4 - P = TO-247AC (modified)

5 - U = Ultrafast recovery

6 - Voltage rating (06 = 600 V)

7 - H = AEC-Q101 qualified

8 - Environmental digit

N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

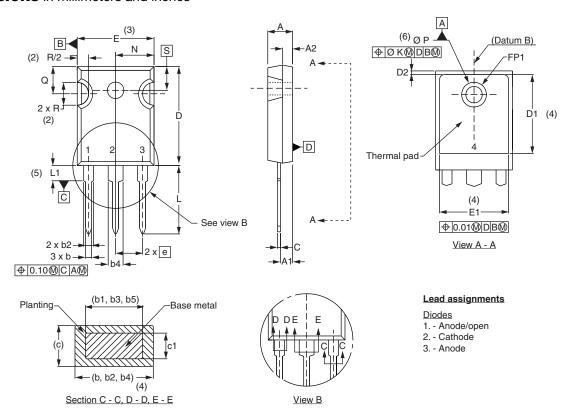
ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-60EPU06HN3	25	500	Antistatic plastic tube				
VS-60APU06HN3	25	500	Antistatic plastic tube				

LINKS TO RELATED DOCUMENTS					
Dimensions	TO-247AC modified	www.vishay.com/doc?95253			
Differsions	TO-247AC	www.vishay.com/doc?95223			
Part marking information	TO-247AC modified	www.vishay.com/doc?95442			
Fait marking imormation	TO-247AC	www.vishay.com/doc?95007			



Vishay Semiconductors

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	MILLIMETERS		HES	NOTES	SY
STIVIBOL	MIN.	MAX.	MAX. MIN. MAX.		NOTES	31
Α	4.65	5.31	0.183	0.209		
A1	2.21	2.59	0.087	0.102		
A2	1.50	2.49	0.059	0.098		
b	0.99	1.40	0.039	0.055		
b1	0.99	1.35	0.039	0.053		
b2	1.65	2.39	0.065	0.094		
b3	1.65	2.37	0.065	0.094		
b4	2.59	3.43	0.102	0.135		
b5	2.59	3.38	0.102	0.133		
С	0.38	0.86	0.015	0.034		
c1	0.38	0.76	0.015	0.030		
D	19.71	20.70	0.776	0.815	3	
D1	13.08	-	0.515	-	4	

SYMBOL	MILLIMETERS		INC	INCHES		
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	
D2	0.51	1.30	0.020	0.051		
E	15.29	15.87	0.602	0.625	3	
E1	13.72	-	0.540	-		
е	5.46	BSC	0.215	BSC		
FK	2.	54	0.0)10		
L	14.20	16.10	0.559	0.634		
L1	3.71	4.29	0.146	0.169		
N	7.62	BSC	0.3			
ΦР	3.56	3.66	0.14	0.144		
ФР1	1	6.98	-	0.275		
Q	5.31	5.69	0.209	0.224		
R	4.52	5.49	1.78	0.216		
S	5.51	BSC	0.217	BSC		

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional

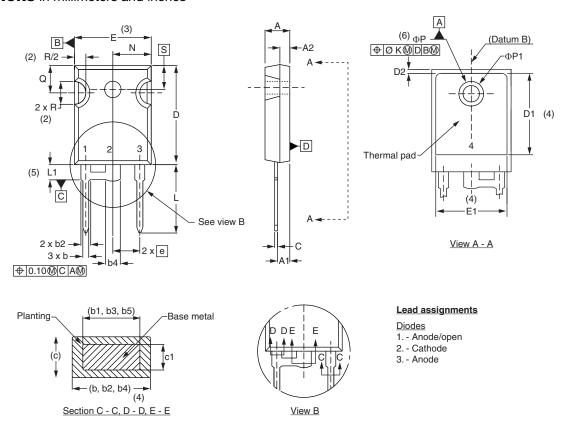
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC outline TO-247 with exception of dimension c

⁽³⁾ Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body



Vishay Semiconductors

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		HES NOTES		SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209			D2	0.51	1.30	0.020	0.051	
A1	2.21	2.59	0.087	0.102			E	15.29	15.87	0.602	0.625	3
A2	1.50	2.49	0.059	0.098			E1	13.72	-	0.540	-	
b	0.99	1.40	0.039	0.055			е	5.46	BSC	0.215	BSC	
b1	0.99	1.35	0.039	0.053			ΦК	2.	54	0.0)10	
b2	1.65	2.39	0.065	0.094			L	14.20	16.10	0.559	0.634	
b3	1.65	2.37	0.065	0.094			L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135			N	7.62	BSC	0	.3	
b5	2.59	3.38	0.102	0.133			ΦР	3.56	3.66	0.14	0.144	
С	0.38	0.86	0.015	0.034			ФР1	-	6.98	-	0.275	
c1	0.38	0.76	0.015	0.030			Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3		R	4.52	5.49	1.78	0.216	
D1	13.08	-	0.515	-	4		S	5.51	BSC	0.217	BSC	

Notes

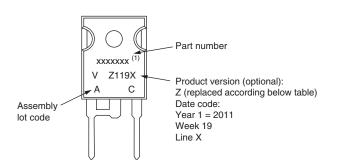
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- (2) Contour of slot optional
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- $^{(7)}\,$ Outline conforms to JEDEC outline TO-247 with exception of dimension c



Part Marking Information

Vishay Semiconductors

TO-247AC modified E



Example: This is a xxxxxxx (1) with assembly lot code AC,

assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Note

(1) If part number contain "H" as last digit, product is AEC-Q101 qualified

ENVIRONMENTAL NAMING CODE (Z)	PRODUCT DEFINITION		
A	Termination lead (Pb)-free		
В	Totally lead (Pb)-free		
E	RoHS compliant and termination lead (Pb)-free		
F	RoHS compliant and totally lead (Pb)-free		
M	Halogen-free, RoHS compliant and termination lead (Pb)-free		
N	Halogen-free, RoHS compliant and totally lead (Pb)-free		
G Green			



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Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000

Mouser Electronics

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VS-60APU06HN3 VS-60EPU06HN3